

Press Release**Heraeus Electronics Wins 2025 Global Technology Award for Its Module Attach Sinter Paste mAgic® PE360**

Hanau, November 2025 – Heraeus Electronics has won the 2025 Global Technology Award in the Thermal Interface Materials category for its large area sinter paste mAgic® PE360. The award was presented during a ceremony at productronica in Munich, Germany, on Tuesday, November 18, 2025.

The mAgic® PE360 was awarded for setting a new benchmark in module attach sintering by delivering uniform attachment and highly reliable thermal paths across large module surfaces—solving one of the industry’s most persistent challenges. Unlike conventional sintering materials that require high pressure and complex handling, PE360 sinters at low pressure and temperature, lowering equipment costs and simplifying production.

Available in both printing (PE360P) and dispensing (PE361D) formats, PE360 offers rare design flexibility while maintaining top-tier performance standards. This dual-format versatility makes it particularly valuable for manufacturers operating across varied assembly processes.

Engineered for exceptional thermal and mechanical performance, PE360 demonstrates outstanding shear strength—even on large bonding areas—producing robust joints with minimal voiding. In thermal cycling tests (-50°C to +150°C, >1000cycles), it has shown superior reliability. With sintering parameters of ~210C and ~10MPa on silver surfaces, PE360 meets or exceeds the performance of traditional sintering materials and far outperforms solder-based interconnects in harsh operating environments.

“mAgic® PE360 was designed to break through long-standing barriers in large area sintering, combining ease of integration, reliability, and overall module efficiency,” said Florian Seifert, Global Product Manager at Heraeus Electronics. “Winning this award highlights how we’re enabling customers to move beyond traditional soldering to next-generation sinter-based interconnects.”

The sinter paste has been successfully qualified in automotive projects. By simplifying process steps and improving performance, mAgic® PE360 is paving the way for broader adoption of silver sintering in automotive, industrial, and renewable energy applications—empowering manufacturers to achieve faster time to market with more robust, reliable products.

Since 2005, the prestigious Global Technology Awards have recognized the absolute best new innovations in the printed circuit assembly and packaging industries. It brings together the global SMT and advanced packaging industry in a celebration of the companies and people that are achieving the highest standards and driving our industry forward. For more information, visit www.globalsmt.net.

For more information about Heraeus Electronics and mAgic® PE360, visit www.heraeus-electronics.com.

About Heraeus

Heraeus is a globally active, family-owned technology group. Based in Hanau, Germany, the company comprises 15 operating companies whose products and services span the Business Areas of Metals & Recycling, Healthcare, Semiconductor & Electronics, and Industrials. In fiscal year 2024, Heraeus generated revenues of €29.4 billion and employed roughly 15,200 people across 40 countries. This makes Heraeus one of the top ten largest family-owned enterprises in Germany.

MATERIALS. INNOVATIONS. FOR GENERATIONS.

About Heraeus Electronics

Heraeus Electronics is a leading manufacturer of materials for the assembly and packaging of devices in the electronics industry. The company develops material solutions for the automotive, power electronics and advanced semiconductor packaging market and offers its customers a broad product portfolio - from materials and material systems to services.

For more information, contact:

Heraeus Electronics

Anja Ziegler

Head of Marketing Communication

Anja.Ziegler@heraeus.com